

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. No.	:	10/549356	Confirmation No. 1717
Applicant (s)	:	Baikerikar, et al.	
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Examiner	:	Fletcher III, William P.	
Title	:	ORGANOSILICATE RESIN FORMULATION OF RESIN IN MICROELECTRONIC DEVICES	
Docket No.	:	62657A	
Customer No.	:	00109	

Sir:

RESPONSE TO RESTRICTION REQUIREMENT

Responsive to the Restriction Requirement dated December 29, 2009, please amend the claims as detailed hereinafter and reconsider the claims in view of the arguments presented hereinafter.

Amendment to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Original) A curable organosilicate composition that is usefully employed in the formation of a hardmask, etchstop, antireflective, adhesion promoting, or other layer in the fabrication of electronic devices comprising:
 - (a) an alkoxy or acyloxy silane having at least one group containing ethylenic unsaturation which group is bonded to the silicon atom
 - (b) an alkoxy or acyloxy silane having at least one group containing an aromatic ring which group is bonded to the silicon atom,
 - (c) a latent acid catalyst, and
 - (d) optionally an alkoxy or acyloxy silane having at least one C₁-C₆ alkyl group bonded to the silicon atom.
2. (Original) The composition of claim 1 wherein the first silane (a) is a vinyl acetoxy silane and the second silane (b) is an arylalkoxysilane.
3. (Original) The composition of claim 1 wherein the combination comprises
 - (a) 50-95 mole percent silanes of the formula